

ABSTRACT

The chip module comprises a semiconductor chip, which is fixed on a main side of a substrate of planar extent. A component, which is provided for taking up, emitting, reflecting or partially shielding electromagnetic radiation, e.g., a radiation sensor or an optical display device (display), is provided on the same main side of the substrate and is connected to the semiconductor chip. The substrate is transmissive to the relevant radiation to a sufficient extent and at least in a region occupied by the component.